

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.2	100.0	3.9
			<b>Subtotal</b>	<b>0.2</b>	<b>100</b>	<b>3.9</b>
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0	5.0	0.05
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.03
	Lead alloy	Lead (Pb)	7439-92-1	0.05	92.5	0.93
			<b>Subtotal</b>	<b>0.05</b>	<b>100</b>	<b>1.01</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.04	100.0	0.73
			<b>Subtotal</b>	<b>0.04</b>	<b>100</b>	<b>0.73</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.4
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.06	0.8
	Copper alloy	Copper (Cu)	7440-50-8	67.37	99.91	1338.79
			<b>Subtotal</b>	<b>67.43</b>	<b>100</b>	<b>1339.99</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.04	100.0	20.68
			<b>Subtotal</b>	<b>1.04</b>	<b>100</b>	<b>20.68</b>
Mould Compound		Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	0.22	0.7	4.35
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.87	6.0	37.26
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.75	12.0	74.52
	Filler	Silica fused	60676-86-0	21.87	70.0	434.7
	Carbon Black	Carbon black	1333-86-4	0.09	0.3	1.86
	Filler	Misc. Silica compounds (generic)	14808-60-7	3.12	10.0	62.1
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.31	1.0	6.21
			<b>Subtotal</b>	<b>31.23</b>	<b>100</b>	<b>621</b>
			<b>Total</b>	<b>99.99</b>	<b>100</b>	<b>1987.31</b>

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